

## CLAIMS AMENDMENTS

1. (original) A flip-chip die having an active surface with a plurality of core power/ground pads, at least one signal pad ring, at least one power pad ring and at least one ground pad ring thereon, wherein the core power/ground pads are located in the central region of the die while the signal pad ring, the power pad ring and the ground pad ring are located outside the central power/ground pad region but concentric to the central power/ground pad region.

2. (original) The flip-chip die of claim 1, wherein the signal pad ring encloses a plurality of die pads such that over 50% of the die pads within the signal pad ring is signal pads.

3. (original) The flip-chip die of claim 1, wherein the signal pad ring encloses a plurality of die pads and the die pads are positioned as a multiple of rings.

4. (original) The flip-chip die of claim 1, wherein the power pad ring includes a plurality of die pads such that over 50% of the die pads within the power pad ring is power pads.

5. (original) The flip-chip die of claim 1, wherein the power pad ring encloses a plurality of die pads and the die pads are positioned as a multiple of rings.

6. (original) The flip-chip die of claim 1, wherein the ground pad ring includes a plurality of die pads such that over 50% of the die pads within the ground pad ring is ground pads.

7. (original) The flip-chip die of claim 1, wherein the ground pad ring encloses a plurality of die pads and the die pads are positioned as a multiple of rings.

Claims 8-25 (canceled)